

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

1t2940ims#trpbf

(Engineering Calculation)

MSOP

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**TOTAL MASS (g) : 0.037918**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.002855	1000000	75294.0078125		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.013845	975000	365129.8125		
		Iron (Fe)	7439-89-6	0.000341	24000	8993.08496094		
		Phosphorus (P)	7723-14-0	0.000004	300	105.490722656		
		Zinc (Zn)	7440-66-6	0.000010	700	263.726806641		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.014200</b>	<b>1000000</b>	<b>374492.09375</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000710	1000000	18725.2636719		
		<b>External Plating Total:</b>				<b>0.000710</b>	<b>1000000</b>	<b>18725.2636719</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000086	1000000	2268.05078125		
<b>Internal Plating Total:</b>				<b>0.000086</b>	<b>1000000</b>	<b>2268.05078125</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000879	750000	23181.5878906		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000293	250000	7727.1953125		
<b>Die Attach Total:</b>				<b>0.001172</b>	<b>1000000</b>	<b>30908.78125</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.002439	130000	64322.9726562		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.015571	830000	410649.03125		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000657	35000	17326.8515625		
		Carbon Black (C)	1333-86-4	0.000094	5000	2479.03222656		
		<b>Encapsulation Total:</b>				<b>0.018761</b>	<b>1000000</b>	<b>494777.875</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000134	1000000	3533.93969727		
					<b>TOTAL MASS (g) :</b>	<b>0.037918</b>		